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US 3740830 A	19730626	19730626 BRAZING CERAMICS	228/121	Campbell, Jr., Albert Eva
US 4447392 A	19840508	19840508 Ductile silver based brazing alloys containing a reactive metal and manganese or germanium or mixty 420/501	tu 420/501	Mizuhara, Howard
US 4606980 A	19860819	19860819 Ductile aluminum based brazing foil containing reactive metals and copper	428/606	Mizuhara, Howard
US 4643875 A	19870217	19870217 Tin based ductile brazing alloys	420/502	Mizuhara, Howard
US 4749594 A	19880607	19880607 Method for coating surfaces with hard substances	427/190	Malikowski, Willi et al.
US 4835593 A	19890530	19890530 Multilayer thin film metallurgy for pin brazing	174/52.4	Arnold, Anthony F. et al.
US 5009357 A	19910423	19910423 Joining of ceramic components to metal components	228/122.1	228/122.1 Baker, Derrick J. et al.
US 5176762 A	19930105	19930105 Age hardenable beta titanium alloy	148/407	Berczik, Douglas M.
US 5273832 A	19931228	19931228 Gold-nickel-vanadium braze joint	428/621	Mizuhara, Howard et al.
US 5301861 A	19940412	19940412 Gold-nickel-vanadium brazing materials	228/121	Mizuhara, Howard et al.
US 5523159 A	19960604	19960604 Brazing of diamond film to tungsten carbide	428/408	Kapoor, Rakesh R. et al.
US 5547121 A	19960820	19960820 Brazing of diamond film to tungsten carbide	228/121	Kapoor, Rakesh R. et al.
US 5567525 A	19961022	19961022 Brazing of diamond film to tungsten carbide	428/408	Kapoor, Rakesh R. et al.
US 6106960 A	20000822	20000822 Joined articles, corrosion-resistant joining materials and process for producing joined articles	428/627	Fujii, Tomoyuki et al.
US 6131796 A	20001017	20001017 Direct brazing of refractory metal features	228/122.1	228/122.1 Kaja, Suryanarayana et a
US 4946376 A	19900807	19900807 Backside metallization scheme for semiconductor devices	428/620	Sharma, Ravinder K. et a
US 4568384 A	19860204	19860204 Method for making Ag/Pd electroding powder	419/6	Maher, Galeb H.
US 4272754 A	19810609	19810609 Thin film varistor	338/21	Lou, Liang F.
US 4448806 A	19840515	19840515 Solderable largely base metal electrodes for metal oxide varistors	427/102	Levinson, Lionel M.
US 3903494 A	19750902	19750902 Metal oxide varistor with coating that enhances contact adhesion	338/20	May, John E.
US 6519129 B1	20030211	20030211 Surge arrester module with bonded component stack	361/117	Ramarge, Michael M. et a
US 6483685 B1	20021119	US 6483685 B1 20021119 Compliant joint between electrical components	361/118	Ramarge, Michael M. et a
US 5392982 A	19950228	19950228 Ceramic bonding method	228/124.5	228/124.5 Li, Chou H.
US 4369063 A	19830118	19830118 Silver containing conductive coatings	106/1.14	106/1.14 McGowan, Jr., Earsel
US 5091820 A	19920225	19920225 Ceramic piezoelectric element with electrodes formed by reduction	361/304	361/304 Iwaya, Shouichi et al.
US 5039452 A	19910813	19910813 Metal oxide varistors, precursor powder compositions and methods for preparing same	252/519.5	252/519.5 Thompson, Mark S. et al
US 4394171 A	19830719	19830719 Thick film conductor compositions	106/1.14	Nair, Kumaran M.
US 4414143 A	19831108	19831108 Conductor compositions	252/514	Felten, John J.
US 5973034 A	19991026	19991026 (Oxide or sulfide) powder epoxy (meth) acrylate w/glass and/or metal	523/458	Mori, Satoshi et al.
US 5397660 A	19950314	19950314 Laser sealed solid electrolyte cell housed within a ceramic frame and the method for producing it	429/163	Rossoll, Mary P. et al.

L Number	Hits	Search Text	DB	Time stamp
7	126	ceramic adj1 (substrate component) and (bond\$3 or braz\$3) and silver with metal with oxide and composit\$3	USPAT; EPO; JPO; DERWENT; IBM TDB	2003/03/31 09:51
8	64	(ceramic adjl (substrate component) and (bond\$3 or braz\$3) and silver with metal with oxide and composit\$3) and powder and paste	USPAT; EPO; JPO; DERWENT; IBM TDB	2003/03/31 09:51
9	9	((ceramic adj1 (substrate component) and (bond\$3 or braz\$3) and silver with metal with oxide and composit\$3) and powder and paste) and foil	USPAT; EPO; JPO; DERWENT; IBM TDB	2003/03/31 10:00
11	1	(((ceramic adj1 (substrate component) and (bond\$3 or braz\$3) and silver with metal with oxide and composit\$3) and powder and paste) and ceramic with ceramic) and silver near2 foil	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/03/31 10:01
10	64	((ceramic adj1 (substrate component) and (bond\$3 or braz\$3) and silver with metal with oxide and composit\$3) and powder and paste) and ceramic with ceramic	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/03/31 10:11
16	3	(((ceramic adj1 (substrate component) and (bond\$3 or braz\$3) and silver with metal with oxide and composit\$3) and powder and paste) and ceramic with ceramic) and silver\$1based	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/03/31 11:38
23	15	("2385580" "2530217" "3047409" "3207706" "3440182" "3480566" "3484284" "3497774" "3944696" "3975201" "4002799" "4032350" "4054714" "4101710" "4142203").PN.	USPAT	2003/03/31
24	20	3440182.URPN.	USPAT	2003/03/31
47	6	5720859.URPN.	USPAT	10:22 2003/03/31 10:29
52	10	228/121.1,245,246,248.1,254.ccls. and silver with oxide and ceramic	USPAT; EPO; JPO; DERWENT; IBM TDB	2003/03/31
53	63	228/\$.ccls. and silver with oxide and ceramic	USPAT; EPO; JPO; DERWENT; IBM TDB	2003/03/31 11:41
54	36	(228/\$.ccls. and silver with oxide and ceramic) and heat\$3 and cool\$3	USPAT; EPO; JPO; DERWENT; IBM TDB	2003/03/31 13:53
59	5	5288351.URPN.	USPĀT	2003/03/31
78	5	5288351.URPN.	USPAT	2003/03/31 .
81	43	bond\$3 with ceramic and silver with oxide with metal and ceramic near2 ceramic and powder	USPAT; EPO; JPO; DERWENT; IBM TDB	2003/03/31 13:59
86	26	(bond\$3 with ceramic and silver with oxide with metal and ceramic near2 ceramic and powder) and silver and heat\$3 and bond\$3 and cool\$3	USPAT; EPO; JPO; DERWENT; IBM TDB	2003/03/31 14:01
89	26	((bond\$3 with ceramic and silver with oxide with metal and ceramic near2 ceramic and powder) and silver and heat\$3 and bond\$3 and cool\$3) and oxide	USPAT; EPO; JPO; DERWENT; IBM TDB	2003/03/31 14:02
-	1	("3740830").PN.	USPAT; US-PGPUB	2003/03/25
_	1	("4447392").PN.	USPAT; US-PGPUB	2003/03/25 18:11
_	1	("4606980").PN.	USPAT; US-PGPUB	2003/03/25 18:12

_	1	("4643875").PN.	USPAT;	2003/03/25
			US-PGPUB	18:12
-	1	("4749594").PN.	USPAT;	2003/03/25
	_		US-PGPUB	18:12
-	1	("4835593").PN.	USPAT;	2003/03/25
	_		US-PGPUB	18:13
-	1	("5009357").PN.	USPAT;	2003/03/25
	_	4864767608)	US-PGPUB	18:13
-	1	("5176762").PN.	USPAT;	2003/03/25
		/#5072020#\ DV	US-PGPUB	18:13 2003/03/25
	1	("5273832").PN.	USPAT;	
	1	(UC2010C1U) DM	US-PGPUB	18:13 2003/03/25
-	1	("5301861").PN.	USPAT; US-PGPUB	18:14
	1	("5523159").PN.	USPAT;	2003/03/25
-	1	(5323139).PN.	US-PGPUB	18:14
1_	1	("5547121").PN.	USPAT;	2003/03/25
_	_	(334/121 /.IN.	US-PGPUB	18:14
_	1	("5567525").PN.	USPAT;	2003/03/25
	_	(330/020 /	US-PGPUB	18:14
_	1	4606980.URPN.	USPAT	2003/03/28
				09:22
_	25	4835593.URPN.	USPAT	2003/03/28
				09:23
_	1	5009357.URPN.	USPAT	2003/03/28
				09:27
-	10	5176762.URPN.	USPAT	2003/03/28
				09:27
-	3	3740830.URPN.	USPAT	2003/03/28
				09:33
_	143	29/25.41,25.42,610.1,612,614,616,619,831,8		2003/03/28
		and ceramic and (silver or ag) and oxide	EPO; JPO;	09:58
		with metal	DERWENT;	
			IBM_TDB	0000 (00 (00
-	6	(29/25.41,25.42,610.1,612,614,616,619,831,		2003/03/28
		and ceramic and (silver or ag) and oxide	EPO; JPO;	09:42
		with metal) and vanadium	DERWENT;	
	14	338/\$.ccls. and ceramic and (silver or	IBM_TDB USPAT;	2003/03/28
1	14	ag) and oxide with metal and heat\$3 and	EPO; JPO;	10:03
		cool\$3 and vanadium	DERWENT;	10.03
		COOL53 and Vanadium	IBM TDB	
_	69	338/\$.ccls. and ceramic and (silver or	USPAT;	2003/03/28
		ag) and oxide with metal and heat\$3 and	EPO; JPO;	10:28
1		cool\$3 and bond\$3	DERWENT;	
			IBM TDB	
-	6	3818118.URPN.	USPAT	2003/03/28
				10:10
-	1	5680289.URPN.	USPAT	2003/03/28
				10:11
-	53	("2586285" "2593955" "3328631"	USPAT	2003/03/28
		"3903494" "4100588" "4286743"		10:24
		"4296002" "4316171" "4352140"		
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		"4476513" "4538347" "4656555"		
		"4729053" "4816959" "4825188" "4023433" "4051055" "4023033"		
	1	"4833438" "4851955" "4930039" "5003600" "5113306" "5120517"		
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		"5159158" "5210676" "5214249"		
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		"5936824" "5936825" "5936826"		
		"5959822" "6008975").PN.	1	

_	55	surge adj1 arrester and silver and oxide	USPAT; EPO; JPO; DERWENT;	2003/03/28 10:32
-	0	(surge adj1 arrester and silver and oxide) and ceramic and vanadium	IBM_TDB USPAT; EPO; JPO; DERWENT;	2003/03/28 10:33
-	38.	(surge adj1 arrester and silver and oxide) and ceramic	IBM_TDB USPAT; EPO; JPO; DERWENT;	2003/03/28 10:35
-	1354	(silver or silver\$1based) and ceramic and metal near2 oxide and vanadium	IBM_TDB USPAT; EPO; JPO; DERWENT;	2003/03/28 10:50
-	479	((silver or silver\$1based) and ceramic and metal near2 oxide and vanadium) and bond\$3 and heat\$3 and cool\$3	IBM_TDB USPAT; EPO; JPO; DERWENT;	2003/03/28 10:38
-	133	(((silver or silver\$1based) and ceramic and metal near2 oxide and vanadium) and bond\$3 and heat\$3 and cool\$3) and powder	IBM_TDB USPAT; EPO; JPO; DERWENT;	2003/03/28 10:39
-	45	and paste (silver or silver\$1based) and ceramic and metal near2 oxide near2 powder and vanadium and bond\$3 and heat\$3 and cool\$3	IBM_TDB USPAT; EPO; JPO; DERWENT;	2003/03/28 10:51
-	24	((silver or silver\$1based) and ceramic and metal near2 oxide near2 powder and vanadium and bond\$3 and heat\$3 and	IBM_TDB USPAT; EPO; JPO; DERWENT;	2003/03/28 10:52
-	25	cool\$3) and paste 4111189.URPN.	IBM_TDB USPAT	2003/03/28
-	1	5680289.URPN.	USPAT	2003/03/28
-	16	("4262318" "4424547" "4587592" "4656555" "4729053" "4812944" "4825188" "4833438" "4853670" "4989115" "5043838" "5138517" "5159158" "5291366" "5363266" "5444429").PN.	USPAT	11:35 2003/03/28 11:35
-	61	4109377.URPN.	USPAT	2003/03/28 13:51
_	6	3818118.URPN.	USPAT	2003/03/28 13:59
_	5	("2720573" "5057674" "5166658" "5382938" "5602520").PN.	USPAT	2003/03/28 14:07
_	3	5896264.URPN.	USPAT	2003/03/28 14:07
-	3	5930102.URPN.	USPAT	2003/03/28
_	4	("3899451" "3953373" "3953375" "3959543").PN.	USPAT	2003/03/28
_	1	"5104849".PN.	USPAT	2003/03/28
-	6	5720859.URPN.	USPAT	2003/03/28
-	26	("0928398" "0934704" "1197693" "2429088" "4188651" "4212045" "4271045" "4311520" "4321089" "4324582" "4364021" "4505787" "4514321" "4733018" "4747014" "4987515" "5039452" "5062891" "5091820" "5131941" "5321223" "5407473" "5410135" "5443560" "5471721" "5480834").PN.	USPAT	2003/03/28
_	5	5583734.URPN.	USPAT	2003/03/28 17:46
-	2	5387441.URPN.	USPAT	2003/03/28 17:49

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-	2	5159748.URPN.	USPAT	2003/03/28
	_			17:53
-	7	5128824.URPN.	USPAT	2003/03/28
				18:03
-	244		USPAT;	2003/03/28
		with (metal adj1 oxide) and oxide and	EPO; JPO;	19:04
		bond\$3 and heat\$3 and cool\$3	DERWENT;	
			IBM TDB	
-	0	((29/25.41,25.42,610.1,612,614,616,619,831	,862AEcls.	2003/03/28
		and ceramic and (silver or ag) and oxide	EPO; JPO;	19:04
		with metal) and vanadium) and varistor	DERWENT;	
		·	IBM TDB	
_	1	(ceramic and (silver or silver\$1based)	USPAT;	2003/03/28
		with (metal adj1 oxide) and oxide and	EPO; JPO;	19:06
		bond\$3 and heat\$3 and cool\$3) and	DERWENT;	ļ
		varistor	IBM TDB	
_	174		USPAT;	2003/03/28
		with (metal adj1 oxide) and oxide and	EPO; JPO;	19:06
		bond\$3 and heat\$3 and cool\$3) and coat\$3	DERWENT;	
		and mix\$3	IBM TDB	
_	174		USPAT;	2003/03/28
		with (metal adj1 oxide) and oxide and	EPO; JPO;	19:07
		bond\$3 and heat\$3 and cool\$3) and coat\$3	DERWENT;	
		and mix\$3) and surface	IBM TDB	
_	155		USPAT;	2003/03/28
		with (metal adj1 oxide) and oxide and	EPO; JPO;	19:08
		bond\$3 and heat\$3 and cool\$3) and coat\$3	DERWENT;	
		and mix\$3) and surface) and (contact\$3 or	IBM TDB	
		apply\$3)		
_	115	((((ceramic and (silver or silver\$1based)	USPAT;	2003/03/28
		with (metal adj1 oxide) and oxide and	EPO; JPO;	19:14
		bond\$3 and heat\$3 and cool\$3) and coat\$3	DERWENT;	
	1	and mix\$3) and surface) and (contact\$3 or	IBM TDB	
	1	apply\$3)) and melt\$3		
_	19		USPAT;	2003/03/28
		silver\$1based) with (metal adj1 oxide)	EPO; JPO;	19:29
		and oxide and bond\$3 and heat\$3 and	DERWENT;	13.23
		cool\$3) and coat\$3 and mix\$3) and	IBM TDB	
		surface) and (contact\$3 or apply\$3)) and		
		melt\$3) and resistor		
-	2	6042682.pn.	USPAT;	2003/03/28
	_	00120212	EPO; JPO;	19:29
			DERWENT;	.
			IBM TDB	
_	4	4448806.URPN.	USPAT	2003/03/29
	1			12:36
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1		1		